

N And P-Channel Enhancement Mode MOSFET

Description

The NP4614QR uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

◆ N-channel:

$V_{DS} = 40V$, $I_D = 10A$

$R_{DS(ON)} = 15.5m\Omega$ (typical) @ $V_{GS} = 10V$

$R_{DS(ON)} = 20m\Omega$ (typical) @ $V_{GS} = 4.5V$

P-Channel:

$V_{DS} = -40V$, $I_D = -10A$

$R_{DS(ON)} = 29m\Omega$ (typical) @ $V_{GS} = -10V$

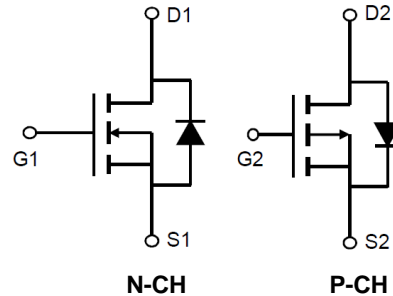
$R_{DS(ON)} = 40m\Omega$ (typical) @ $V_{GS} = -4.5V$

- ◆ Excellent gate charge x $R_{DS(ON)}$ product(FOM)
- ◆ Very low on-resistance $R_{DS(ON)}$
- ◆ 150 °C operating temperature
- ◆ Pb-free lead plating

Application

- ◆ Pch+Nch Complementary MOSFET for DC-FAN
- ◆ H-Bridge application

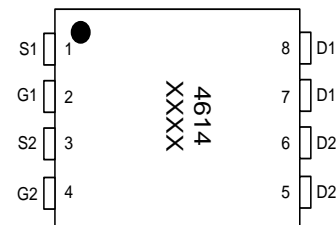
Schematic diagram



Marking and pin assignment

PDFN3×3-8L

(Top View)



Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
NP4614QR-G	-55°C to +150°C	PDFN3*3-8L	5000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit		Unit	
		N	P		
Drain-source voltage	V_{DS}	40	-40	V	
Gate-source voltage	V_{GS}	±20	±20	V	
Operating junction Temperature range	T_j	-55—150	-55—150	°C	
Drain Current-Continuous (Silicon Limited)	$T_A = 25^\circ C$	I_D	10	-10	A
	$T_A = 75^\circ C$		6	-6	
Pulsed Drain Current (Package Limited)	I_{DM}	72	-72	A	

Avalanche Current ^C		I_{AS}, I_{AR}	22	-27	A
Avalanche energy $L=0.1\text{mH}^C$		E_{AS}, E_{AR}	24	36	mJ
Power Dissipation ^B	$T_A=25^\circ\text{C}$	P_D	12	20	W
	$T_A=75^\circ\text{C}$		5	8	
Junction and Storage Temperature Range		T_J, T_{STG}	-55—150		$^\circ\text{C}$

N-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu\text{A}$	40	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{DS}=40V, V_{GS}=0V$	-	-	1	μA
Gate-body leakage	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	± 100	nA
ON Characteristics						
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.73	2.5	V
Drain-source on-state resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=10A$	-	15.5	17	m Ω
		$V_{GS}=4.5V, I_D=10A$	-	20	25	
Forward transconductance	gfs	$V_{DS}=5V, I_D=10A$	-	43	-	S
Dynamic Characteristics						
Input capacitance	C_{ISS}	$V_{DS}=20V, V_{GS}=0V$ $f=1.0\text{MHz}$	-	949	-	pF
Output capacitance	C_{OSS}		-	72	-	
Reverse transfer capacitance	C_{RSS}		-	60	-	
Gate resistance	R_g	$V_{GS}=0V, V_{DS}=0V,$ $f=1.0\text{MHz}$	-	1.6	2.4	Ω
Switching Characteristics						
Turn-on delay time	$t_{D(ON)}$	$V_{DS}=20V$ $V_{GS}=10V$ $R_L=1.5\Omega$ $R_{GEN}=3\Omega$	-	4.4	-	ns
Rise time	t_r		-	9	-	
Turn-off delay time	$t_{D(OFF)}$		-	17	-	
Fall time	t_f		-	6	-	
Total gate charge	Qg	$V_{DS}=20V, I_D=10A$ $V_{GS}=10V$	-	18.8	-	nC
Gate-source charge	Qgs		-	3.4	-	
Gate-drain charge	Qgd		-	3.1	-	

Typical Performance Characteristics

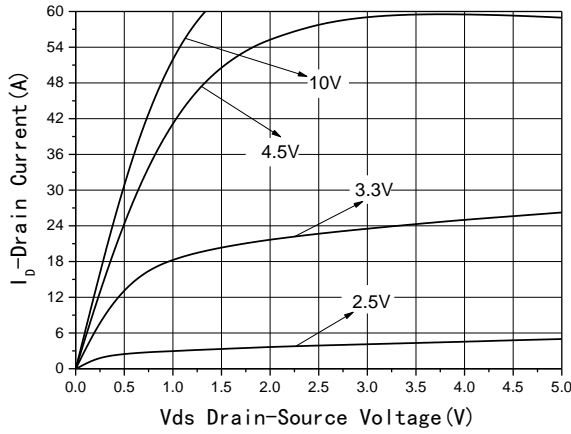


Fig1 Output Characteristics

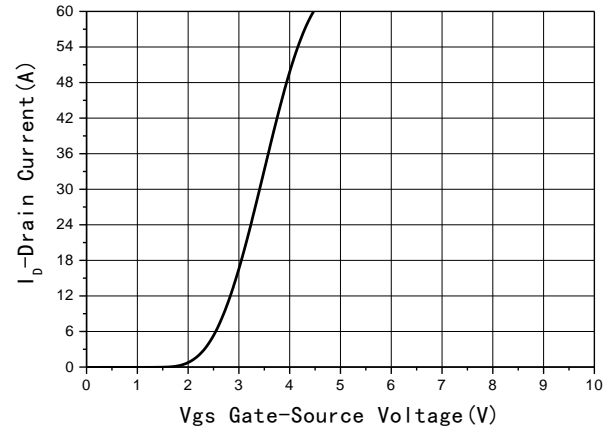


Fig2 Transfer Characteristics

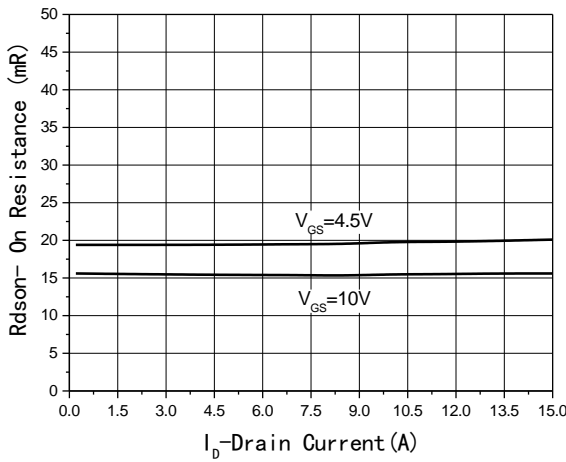


Fig3 $R_{DS(on)}$ -Drain current

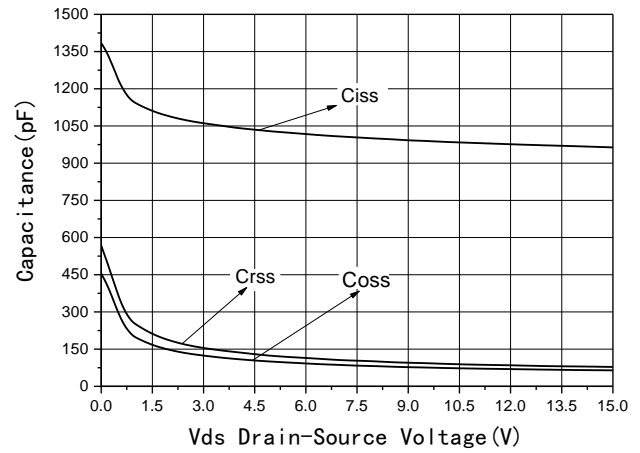


Fig4 Capacitance vs V_{DS}

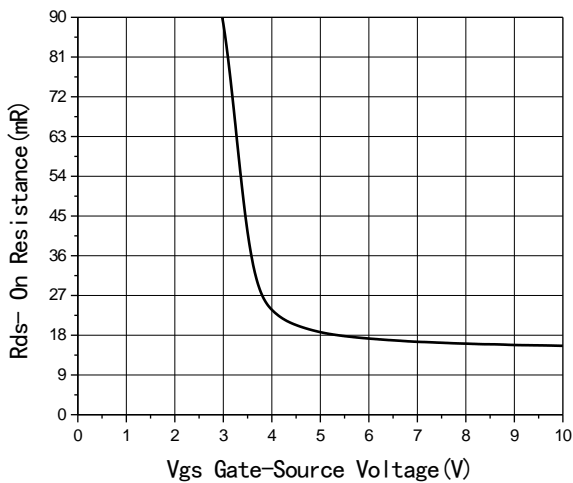


Fig5 $R_{DS(on)}$ -Gate Drain voltage

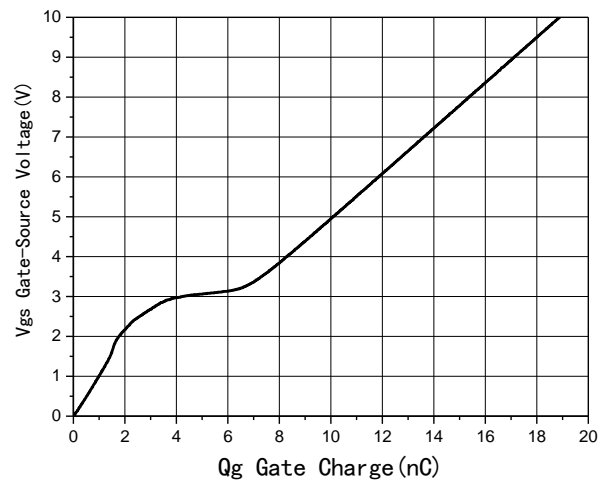


Fig6 Gate Charge

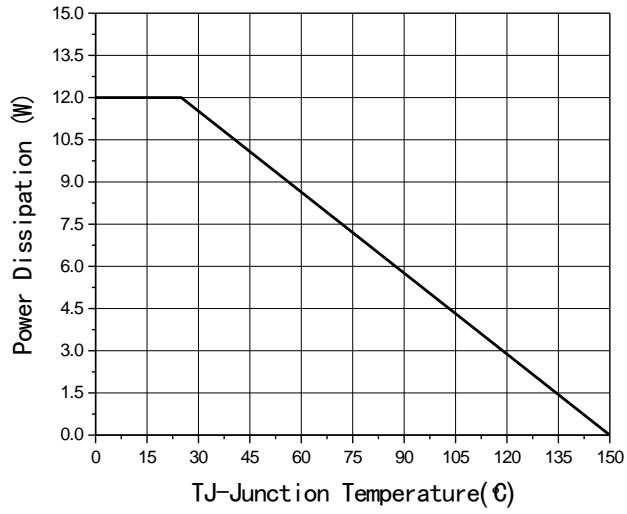


Fig7 Power De-rating

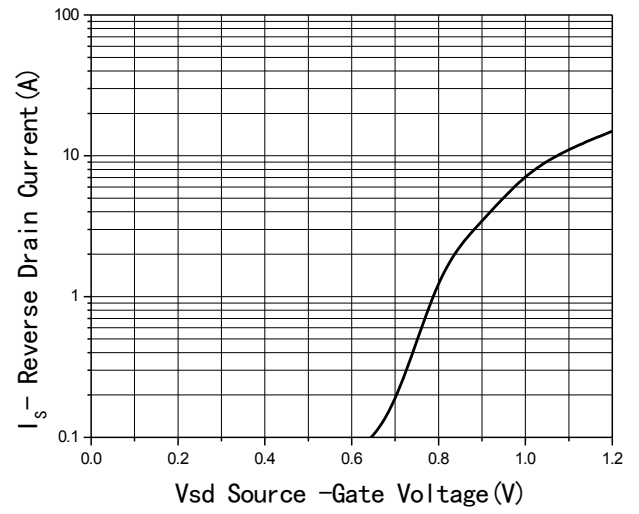


Fig8 Source-Drain Diode Forward

P-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-40	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{DS}=-40V, V_{GS}=0V$	-	-	-1	μA
Gate-body leakage	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	± 100	nA
ON Characteristics						
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-1.6	-2.5	V
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-10A$	-	29	32	m Ω
		$V_{GS}=-4.5V, I_D=-10A$	-	40	46	
Forward transconductance	gfs	$V_{DS}=-5V, I_D=-10A$	-	18	-	S
Dynamic Characteristics						
Input capacitance	C_{ISS}	$V_{DS}=-20V, V_{GS}=0V$ $f=1.0\text{MHz}$	-	1338	-	pF
Output capacitance	C_{OSS}		-	111	-	
Reverse transfer capacitance	C_{RSS}		-	86	-	
Gate resistance	R_g	$V_{GS}=0V, V_{DS}=0V,$ $f=1.0\text{MHz}$	-	4	-	Ω
Switching Characteristics						
Turn-on delay time	$t_{D(on)}$	$V_{DS}=-20V$ $V_{GS}=-10V$ $R_L=2.3\Omega$ $R_{GEN}=3\Omega$	-	10	-	ns
Rise time	t_r		-	5.5	-	
Turn-off delay time	$t_{D(off)}$		-	3.6	-	
Fall time	t_f		-	4.6	-	
Total gate charge	Q_g	$V_{DS}=-20V, I_D=-10A$ $V_{GS}=-10V$	-	23.5	-	nC
Gate-source charge	Q_{gs}		-	4	-	
Gate-drain charge	Q_{gd}		-	3.6	-	

Typical Performance Characteristics

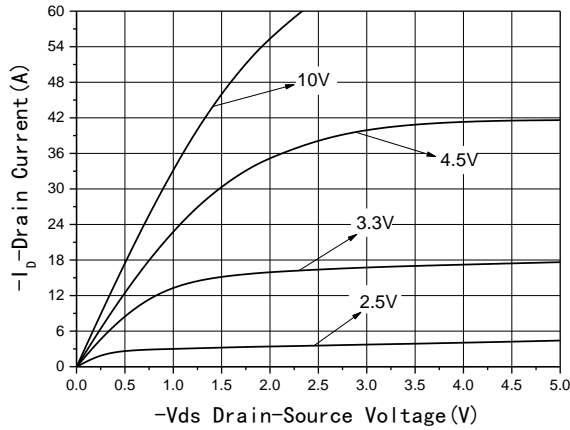


Fig1 Output Characteristics

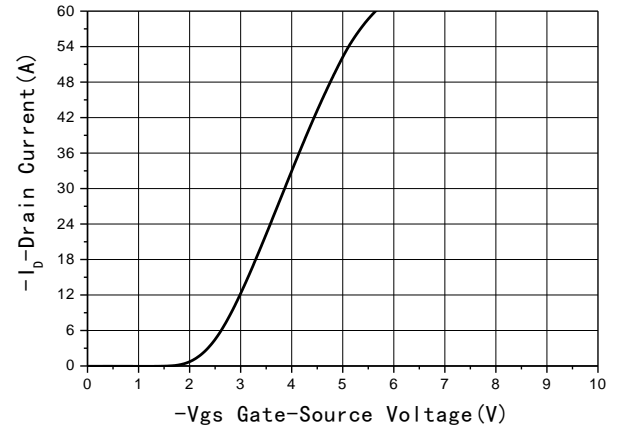


Fig2 Transfer Characteristics

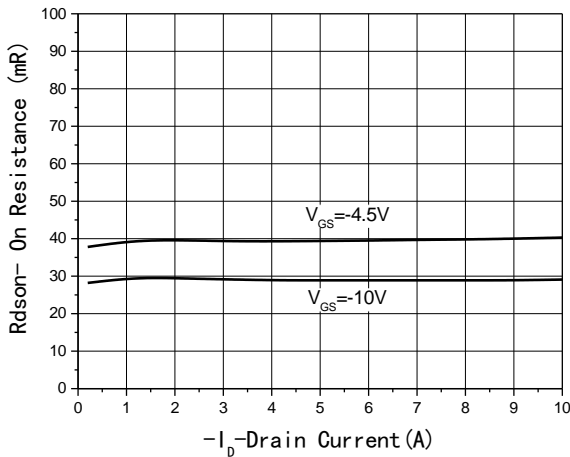


Fig3 Rdson-Drain current

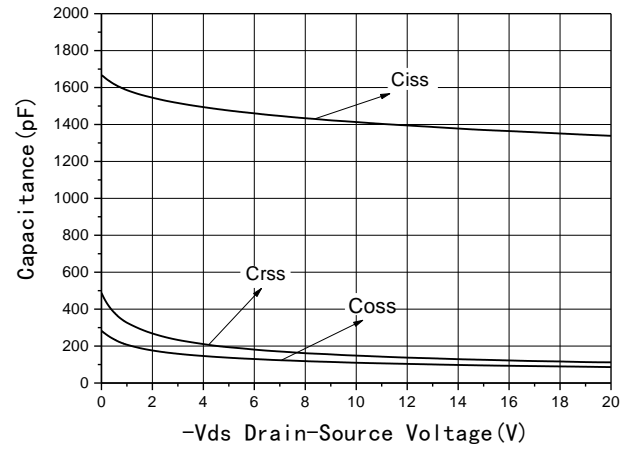


Fig4 Capacitance vs Vds

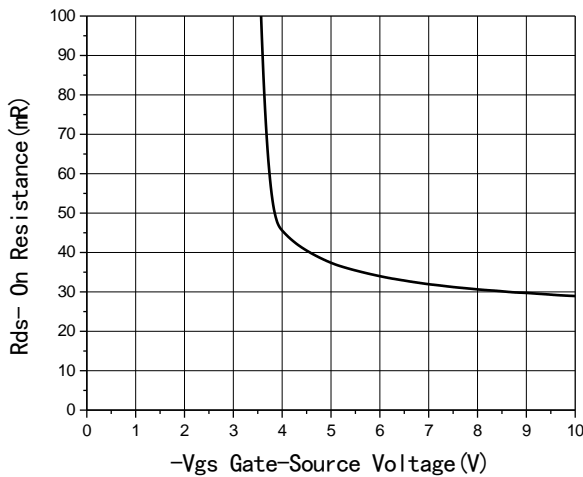


Fig5 Rdson-Gate Drain voltage

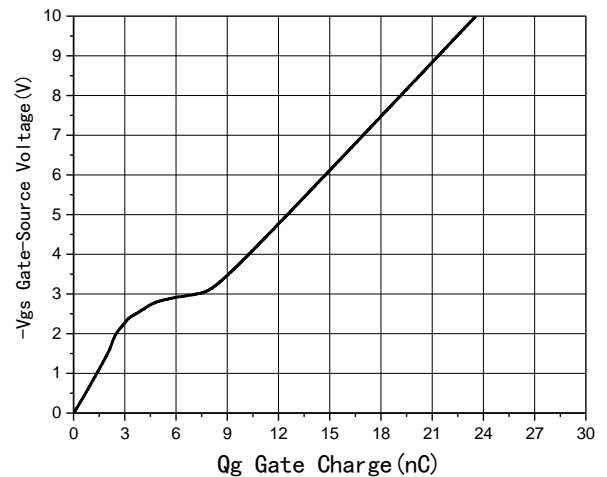


Fig6 Gate Charge

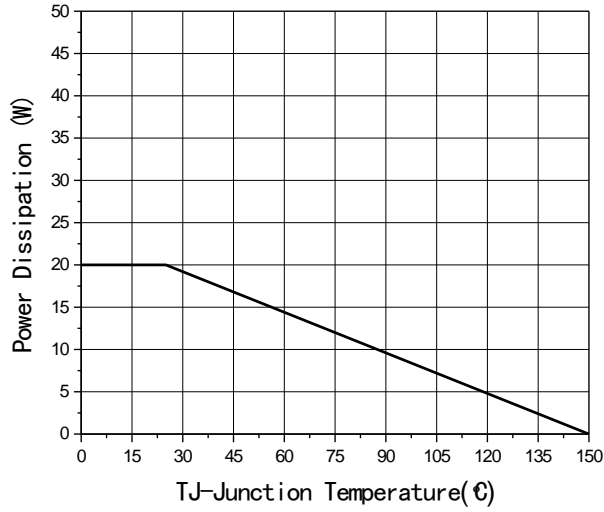


Fig7 Power De-rating

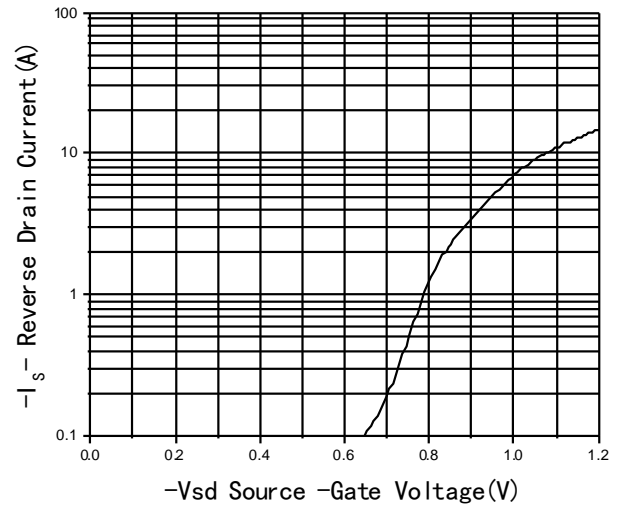
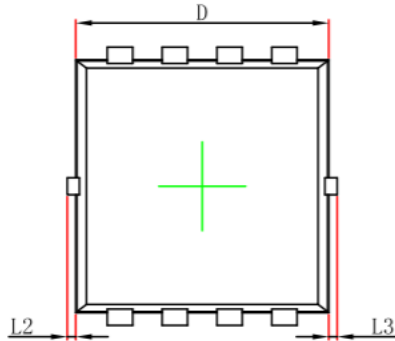


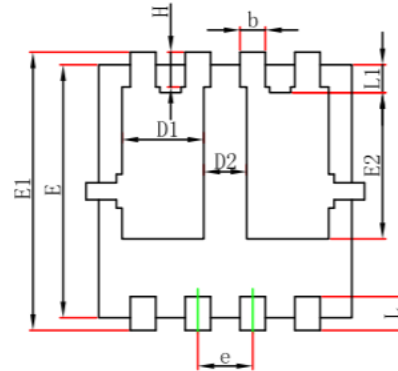
Fig8 Source-Drain Diode Forward

Package Information

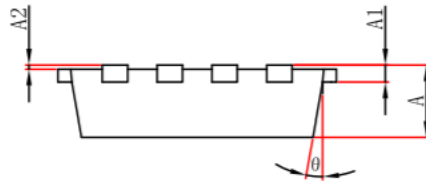
- PDFN3*3-8L



Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	0.935	1.135	0.037	0.045
D2	0.280	0.480	0.011	0.019
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°